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Silicon NPN Epitaxial

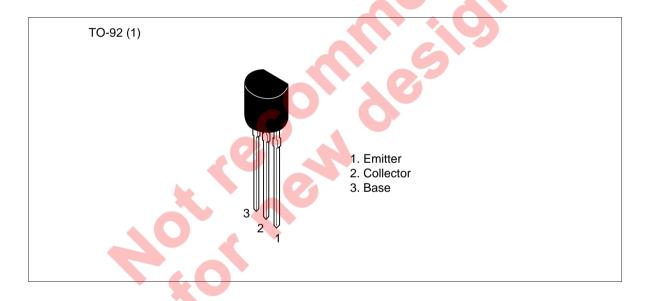


ADE-208-1163 (Z) 1st. Edition Mar. 2001

Application

Low frequency high voltage amplifier

Outline



Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

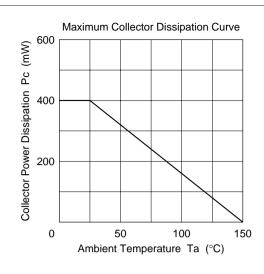
Item	Symbol	2SD2030	2SD2031	Unit
Collector to base voltage	V_{CBO}	160	200	V
Collector to emitter voltage	V_{CEO}	160	200	V
Emitter to base voltage	V_{EBO}	5	5	V
Collector current	I _c	100	100	mA
Collector power dissipation	P _c	400	400	mW
Junction temperature	Tj	150	150	°C
Storage temperature	Tstg	-55 to +150	-55 to +150	°C

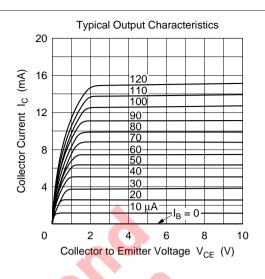
Electrical Characteristics (Ta = 25°C)

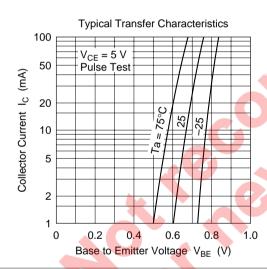
Item		Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	2SD2030	$V_{(BR)CBO}$	160	_	1	V	$I_{c} = 10 \mu A, I_{E} = 0$
	2SD2031	_	200				
Collector to emitter breakdown voltage	2SD2030	$V_{(BR)CEO}$	160		-	V	$I_{\rm C}$ = 1 mA, $R_{\rm BE}$ = ∞
	2SD2031		200				
Emitter to base brea voltage	kdown	$V_{(BR)EBO}$	5	_		V	$I_{E} = 10 \ \mu A, \ I_{C} = 0$
Collector cutoff current	2SD2030	I _{CBO}	_		10	μΑ	$V_{CB} = 140 \text{ V}, I_{E} = 0$
	2SD2031		AK				$V_{CB} = 160 \text{ V}, I_{E} = 0$
DC current transfer ratio		h _{FE1} *1	60	_	200		$V_{CE} = 5 \text{ V}, I_{C} = 10 \text{ mA}$
		h _{FE2}	30	_	_		$V_{CE} = 5 \text{ V}, I_{C} = 1 \text{ mA}$
Base to emitter volta	age	V_{BE}	_	_	1.5	V	$V_{CE} = 5 \text{ V}, I_{C} = 10 \text{ mA}$
Collector to emitter s	saturation	V _{CE(sat)}	_	_	0.5	V	$I_{\rm C}$ = 30 mA, $I_{\rm B}$ = 3 mA
Gain bandwidth product		f _T	_	140	_	MHz	$V_{CE} = 5 \text{ V}, I_{C} = 10 \text{ mA}$
Collector output capacitance		C _{ob}	_	3.8	_	pF	$V_{CB} = 10 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$

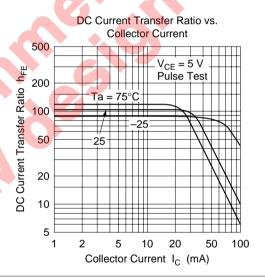
Note: 1. The 2SD2030 and 2SD2031 are grouped by h_{FE1} as follows.

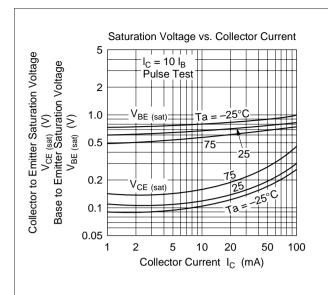
Grade	В	С
h _{FE1}	60 to 120	100 to 200

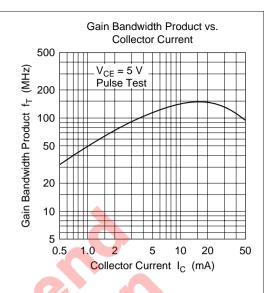


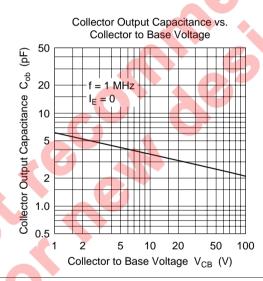




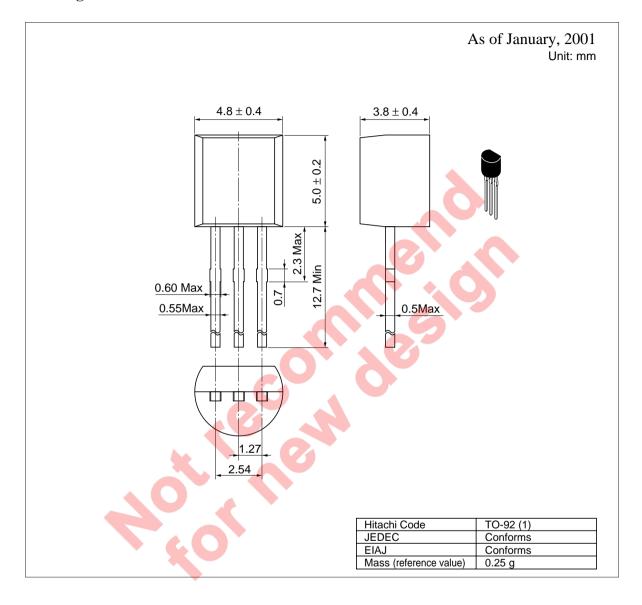








Package Dimensions



5

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Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

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For further information write to:

Hitachi Semiconductor (America) Inc. 179 East Tasman Drive, San Jose,CA 95134 Tel: <1> (408) 433-1990 Germany

Hitachi Europe GmbH Electronic Components Group Dornacher Straße 3 D-85622 Feldkirchen, Munich Fax: <1>(408) 433-0223 Tel: <49> (89) 9 9180-0 Fax: <49> (89) 9 29 30 00

> Hitachi Europe Ltd. Electronic Components Group. Whitebrook Park Lower Cookham Road Maidenhead Berkshire SL6 8YA, United Kingdom Tel: <44> (1628) 585000

Fax: <44> (1628) 585160

Hitachi Asia Ltd. Hitachi Tower 16 Collyer Quay #20-00, Singapore 049318 Tel: <65>-538-6533/538-8577 Fax: <65>-538-6933/538-3877 URL: http://www.hitachi.com.sg

Hitachi Asia Ltd. (Taipei Branch Office) 4/F, No. 167, Tun Hwa North Road, Hung-Kuo Building, Taipei (105), Taiwan Tel: <886>-(2)-2718-3666

Fax: <886>-(2)-2718-8180 Telex: 23222 HAS-TP URL: http://www.hitachi.com.tw Hitachi Asia (Hong Kong) Ltd. Group III (Electronic Components) 7/F., North Tower, World Finance Centre, Harbour City, Canton Road Tsim Sha Tsui, Kowloon, Hong Kong

Tel: <852>-(2)-735-9218 Fax: <852>-(2)-730-0281 URL: http://www.hitachi.com.hk

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